A new line of accessories for MICROCOOL

Rome, August 16th, 2006 – MICROCOOL, a leading company in the IT industry for processor and motherboard component heating management systems, is proud to present the new line of accessories for the most demanding modding lovers introducing the Chomerics heat conductive tapes of the Thermattach® series and the core protective rubbers.

THERMATTACH® T411 consists of a high bond strength pressure-sensitive adhesive with an expanded aluminium mesh carrier layer. The mesh carrier allows the tape to conform to curved surfaces of plastic molded IC packages, providing a high adhesive strength attachment for heat sinks. The high performance silicone PSA allows adhesion to silicone-contaminated plastics and other low energy surfaces. T411 is ideal for fixing large coolers where bonding strength is fundamental. It is particularly indicated to install heavy copper coolers on the BGA memories of the video cards or in general for the perfect adhesion of aluminium or copper coolers on chips encapsulated in plastic packaging, such as chipsets or processors, which due to their slightly concave surfaces and the presence of silicone products on the surface, make other tapes ineffective.

THERMATTACH® T412 consists of a high bond strength, pressure-sensitive acrylic adhesive, loaded with titanium diboride and applied to an expanded aluminium carrier. The combination of filler, expanded metal and embossed surface enhances both tape conformability and thermal performance. T412 is ideal for use where you want to obtain excellent heat sinking by fixing the small to medium size coolers in aluminium or copper to components such as: MOSFET, PLL or BGA chips.

CORE PROTECTIVE RUBBERS are an ideal solution to prevent the processor cores or chipsets, without their own protective packaging, from chipping or breaking during installation of the cooler. The protective rubbers were created in such a way that once subjected to the pressure of the cooler during fixing to the socket or the motherboard, they maintain the object in a perfectly flat position on the core surfaces. You therefore avoid the risk of unloading the weight onto the edges of the chip and causing it to break.